IN THE SPECIFICATION:

Please amend the specification as follows:

Paragraph beginning on page 3, at prenumbered line 15, has been amended as follows:

Referring to Fig. 1, a multi-chip stack flip-chip package 100 in accordance with the first embodiment of the present invention comprises a substrate 110, at least a first flip chip 120, a dummy chip 130 and at least a second flip chip 140. The substrate ~~100~~ 110 is a printed circuit board (PCB) formed by metal foil and glass fiber reinforced resin including BT resin, FR-4 resin or FR-5 resin. The substrate ~~100~~ 110 has a top surface 111 and a bottom surface 112.

Paragraph beginning on page 5, at prenumbered line 18, has been amended as follows:

Referring to Fig. 3, a multi-chip stack flip-chip package 200 in accordance with the second embodiment of the present invention comprises a substrate 210, at least a flip chip 220 and a dummy chip 230. The substrate 210 is a printed circuit board, such as BGA substrate, motherboard or memory module substrate. The substrate 210 has a top ~~surface211.~~ surface 211. The dummy chip 230 has a redistribution layer 231 formed by integrated circuit manufacturing process, and the redistribution layer 231 includes a plurality of bump pads 232, a plurality of peripheral pads 233 and a plurality of integrated circuit traces connecting the bump pads 232 with the peripheral pads 233. The peripheral pads 233 are arranged on the periphery of upper surface of the dummy chip 230 for electrically connecting to the substrate 210. The flip chip 220 is mounted on upper surface of the dummy chip 230 so that the bumps 221 of the flip chip 220 are bonded onto the bump pads 232 of the redistribution layer 213. Preferably the flip chip 220 is mounted on the dummy chip 230 in wafer form to manufacture a chip assembly in advance. The dummy chip 230 is attached to the top surface 211 by epoxy adhesive or PI adhesive film. The dummy chip 230 is configured to be an electrically connecting interface between the flip chip 220 and the substrate 210 to achieve fine pitch flip-chip mounting. Electrically connecting devices 234 connect the peripheral pads 233 of the dummy

chip 230 to the substrate 210 so as to electrically connect the flip chip 220 with the substrate 210 through the dummy chip 230. An insulation compound 240 is formed on the substrate 210 by coating or dispensing to protect the flip chip 220 and the electrically connecting devices 234.